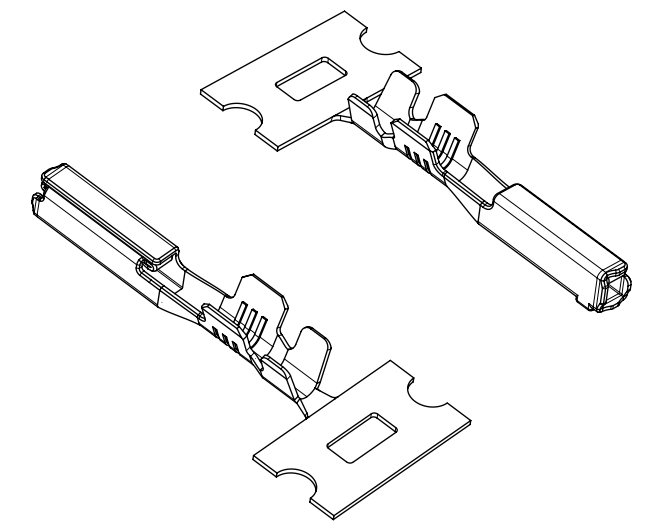
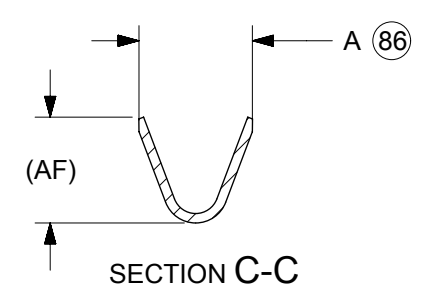
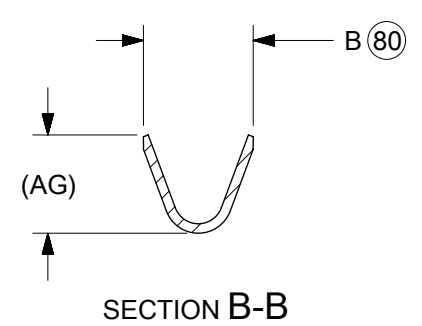
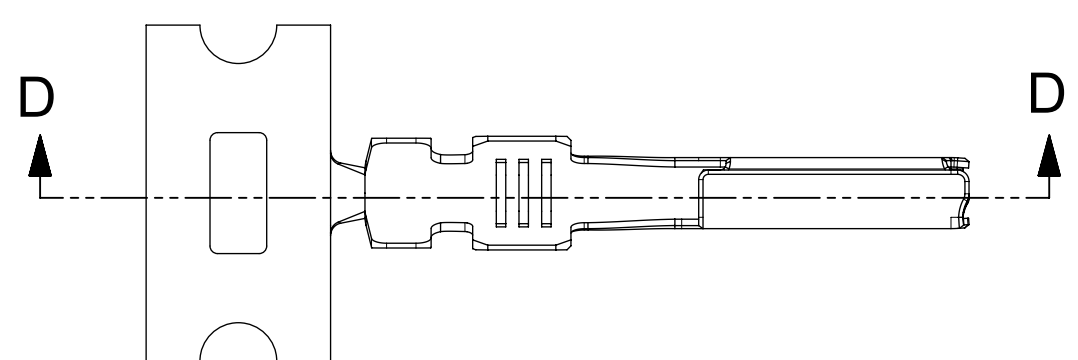


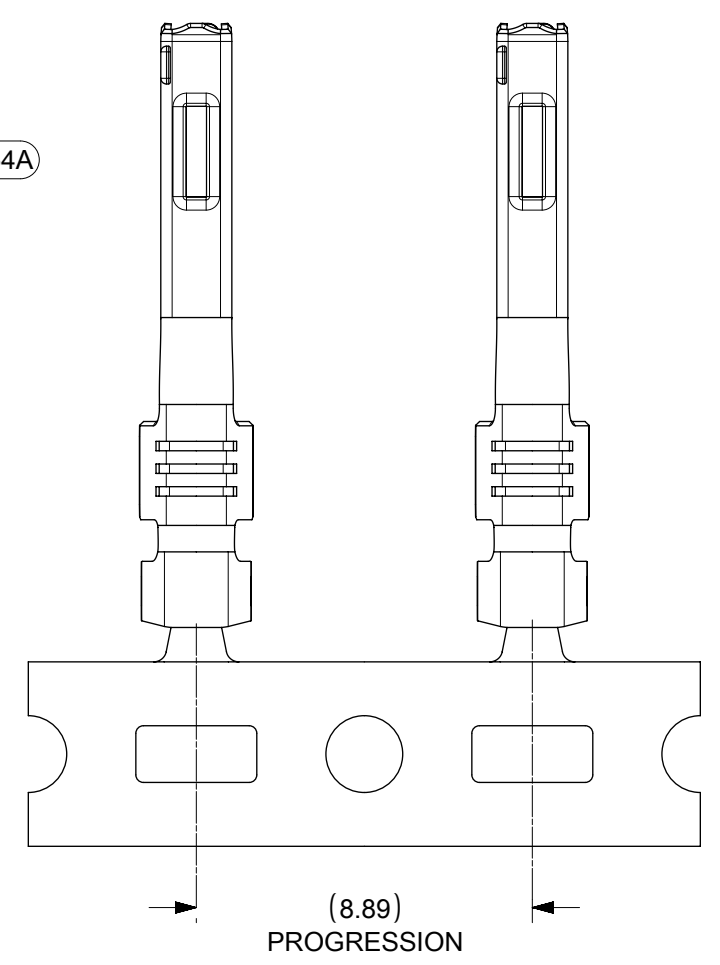
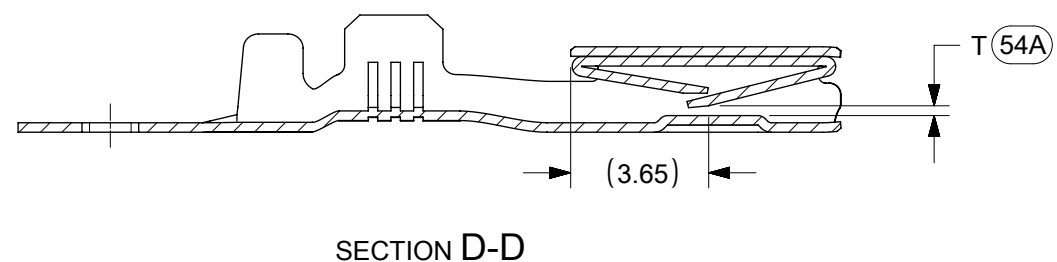
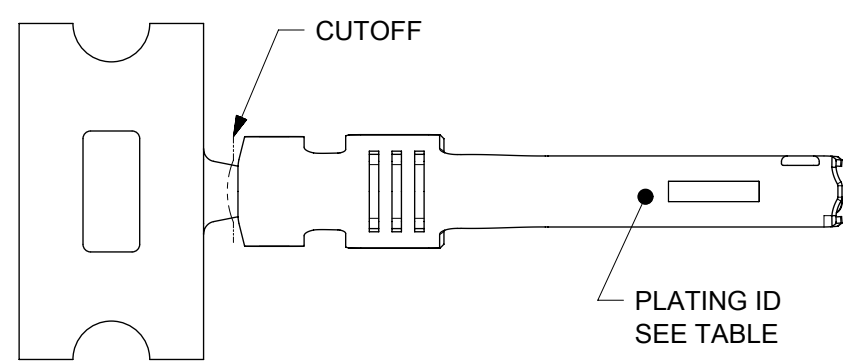
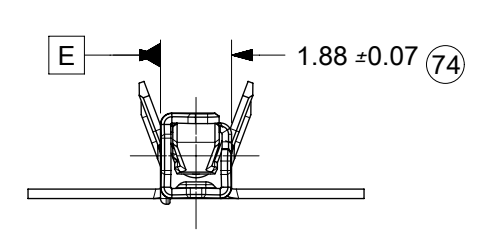
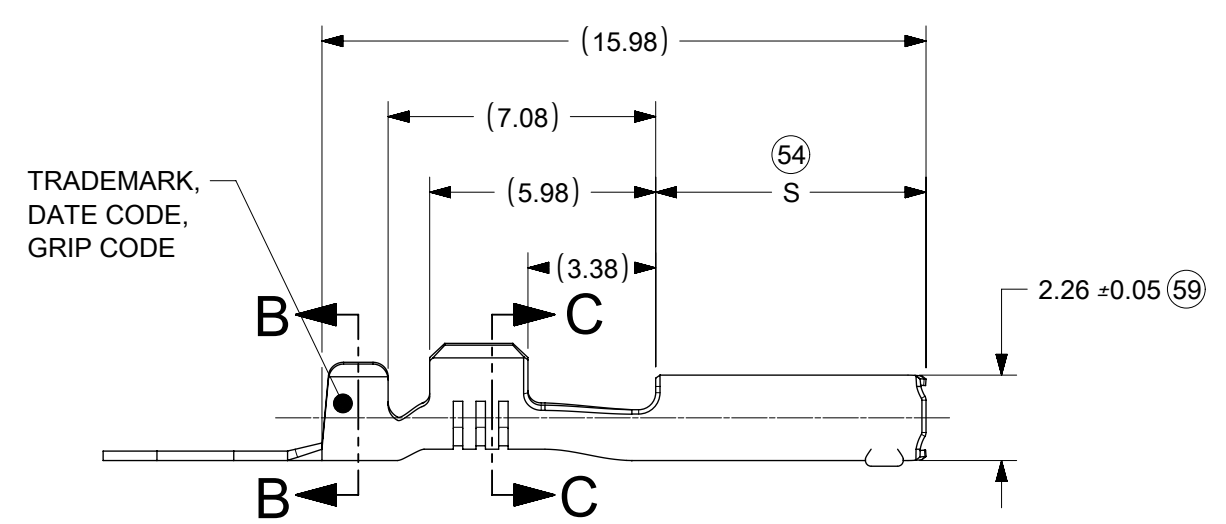


**THE DATASHEET OF**  
**334670003**





ISO VIEWS  
SCALE 3:1



- NOTES: (UNLESS OTHERWISE SPECIFIED)
- MATERIALS: SEE TABLE
  - PACKAGING SPECIFICATION: PK-31300-516 AND PK-30907-759
  - CRIMPING PER APPLICATION SPECIFICATION AS-33468-001
  - CRIMPED LEAD MEETS THE FOLLOWING:
    - SAE/USCAR-21, MAY 2002
    - SAE/USCAR-2, REV. 3, APRIL 2001
    - SAE/USCAR-12, REV. 2
    - GMW #3191 AUGUST 22, 2000 (DRAFT) TEMPERATURE CLASS 3, APPLIES ONLY TO Au PARTS
    - GMW #3191 JANUARY, 2005 TEMPERATURE CLASS 3, APPLIES ONLY TO Ag PARTS
  - PLATING NOTES:
    - TIN PLATING (ENTIRE TERMINAL)
      - ELECTRO REFLOW 1.90 - 3.30 MICROMETERS TIN OVER 0.25 - 0.76 MICROMETERS NICKEL
    - GOLD PLATING
      - UNDERPLATE OVERALL 1.25-2.25 MICROMETERS DUCTILE SULPHAMATE NICKEL
      - ELECTRODEPOSITED GOLD 0.76 - 1.5 MICROMETERS IN CONTACT AREAS
      - ELECTRODEPOSITED TIN MATTE FINISH 2.5 - 4.0 MICROMETERS IN CRIMP AREA
    - SILVER PLATING
      - UNDERPLATE OVERALL 1.25-2.25 MICROMETERS DUCTILE SULPHAMATE NICKEL
      - ELECTRODEPOSITED PURE SILVER 99.5% PURITY SEMI-BRIGHT FINISH WITH NO BRIGHTENERS OR CHROMATES 1.9 - 3.3 MICROMETERS IN CONTACT AREAS
      - ANTI-TARNISH TREATMENT FOR SILVER PLATED AREA: SYNTHETIC HYDROCARBON CONTACT SURFACE FINISH OR EQUIVALENT
      - ELECTRODEPOSITED TIN MATTE FINISH 2.5 - 4.0 MICROMETERS IN CRIMP AREA

WIRE SIZE	GRIP CODE	PART NUMBER	REEL PAYOFF DIRECTION	DIM A	DIM B	DIM S	DIM T	DIM AF	DIM AG	BASE MATERIAL	PLATING ID
22 AWG	A	33468-0002	D	2.3	2.3	7.15 ±0.10	0.26 ±0.07	(2.1)	(2.1)	COPPER ALLOY	Sn Lead Free
		33468-0001	B	2.3	2.3	6.97-7.27	0.26 ±0.07	(2.1)	(2.1)	COPPER ALLOY	Au Lead Free
		33467-0004	D	2.3	2.3	6.97-7.27	0.26 ±0.07	(2.1)	(2.1)	COPPER ALLOY	Ag Lead Free
		34736-1001	D	2.3	2.3	6.97-7.27	0.26 ±0.07	(2.1)	(2.1)	COPPER ALLOY	Ag Lead Free
		34736-2001	B	2.3	2.3	6.97-7.27	0.26 ±0.07	(2.1)	(2.1)	COPPER ALLOY	Ag Lead Free
18/20 AWG	B	33468-0004	D	3.0	2.9	7.15 ±0.10	0.26 ±0.07	(2.8)	(2.6)	COPPER ALLOY	Sn Lead Free
		33468-0003	B	3.0	2.9	6.97-7.27	0.26 ±0.07	(2.8)	(2.6)	COPPER ALLOY	Au Lead Free
		33467-0006	D	3.0	2.9	6.97-7.27	0.26 ±0.07	(2.8)	(2.6)	COPPER ALLOY	Ag Lead Free
		33467-0005	B	3.0	2.9	6.97-7.27	0.26 ±0.07	(2.8)	(2.6)	COPPER ALLOY	Ag Lead Free
		34736-1002	D	3.0	2.9	6.97-7.27	0.26 ±0.07	(2.8)	(2.6)	COPPER ALLOY	Ag Lead Free
34736-2002	B	3.0	2.9	6.97-7.27	0.26 ±0.07	(2.8)	(2.6)	COPPER ALLOY	Ag Lead Free		

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

DIMENSION UNITS	SCALE	CURRENT REV DESC:		<b>molex</b>
mm	5:1			
GENERAL TOLERANCES (UNLESS SPECIFIED)		EC NO: 601885		MX64 SAE RECEPTACLE TERMINAL
ANGULAR TOL	± 3	DRWN: NVENKATESHSH	2018/05/31	
4 PLACES	±	CHK'D: JPRUNEAU	2018/08/09	
3 PLACES	±	APPR: TOMSMITH	2018/08/13	PRODUCT CUSTOMER DRAWING
2 PLACES	± 0.10	INITIAL REVISION:		DOCUMENT NUMBER
1 PLACE	± 0.3	DRWN: DHEMNANI	2007/04/12	SD-33468-001
0 PLACES	±	APPR: BMOSE	2007/04/13	DOC TYPE
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIRD ANGLE PROJECTION	DRAWING	SERIES	DOC PART
		C-SIZE	33468	REVISION
DOCUMENT STATUS	P1	RELEASE DATE	2018/08/13 12:08:30	MATERIAL NUMBER
				SEE TABLE
				CUSTOMER
				GENERAL MARKET
				SHEET NUMBER
				1 OF 1

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